

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings of claims in the application:

Listing of Claims:

1. (Original) A die with text deposited upon the die using semiconductor processing techniques, the die comprising:

a substrate which is cut from a wafer comprising a plurality of substrates;

a first paragraph in contact with the substrate; and

a second paragraph in contact with the substrate and aligned with the first paragraph in a column.

2. (Original) The die with text deposited upon the die using semiconductor processing techniques of claim 1, wherein:

the substrate is a semiconductor substrate; and

text in the column is comprised of one or more of a metal, an oxide, a polysemiconductor and a photoresist.

3. (Original) The die with text deposited upon the die using semiconductor processing techniques of claim 1, wherein the first and second paragraphs are comprised of a plurality of characters.

4. (Original) The die with text deposited upon the die using semiconductor processing techniques of claim 3, wherein each of the plurality of characters is comprised of a plurality of primitives.

5. (Original) The die with text deposited upon the die using semiconductor processing techniques of claim 1, the die further comprising:

- a first character appearing in a first color; and
- a second character appearing in a second color.

6. (Original) The die with text deposited upon the die using semiconductor processing techniques of claim 1, the die further comprising an image on the substrate.

7-34. (Cancelled)

35. (Previously Presented) The die with text deposited upon the die using semiconductor processing techniques of claim 1, the die further comprising a third paragraph on the substrate, wherein the second and third paragraphs are arranged in two columns on the substrate.

36. (Currently Amended) The die with text deposited upon the die using semiconductor processing techniques of claim 1, wherein:

a radiation source configured to operatively engage engages the substrate;
a mask corresponding to is generated from an electronic file;
the mask configured to operatively engage engages the radiation source and the substrate; and

the mask corresponding to includes a first and second paragraphs arranged in a column.

37. (Previously Presented) The die with text deposited upon the die using semiconductor processing techniques of claim 1, further comprising a silhouette image in contact with the substrate and at least partially overlapping with at least one of the first or second paragraphs.

38. (Previously Presented) A die with information deposited upon the die using semiconductor processing techniques, the die comprising:

a substrate which is cut from a wafer comprising a plurality of substrates;

a first paragraph deposited upon the substrate; and

a second paragraph deposited upon the substrate and aligned with the first paragraph in one or more columns.

39. (Previously Presented) The die with information deposited upon the die using semiconductor processing techniques of claim 38, wherein the first paragraph is derived from an electronic file that comprises a plurality of elements corresponding to characters for the first paragraphs.

40. (Previously Presented) The die with information deposited upon the die using semiconductor processing techniques of claim 39, wherein each character of the first and second paragraphs is comprised of a plurality of rectangles wherein one side of the rectangle is equal in size to the process resolution.

41. (Previously Presented) The die with information deposited upon the die using semiconductor processing techniques of claim 38, wherein the first and second paragraphs are separated by at least one of: a hard return, a tab or an enlarged character.

42. (Previously Presented) The die with information deposited upon the die using semiconductor processing techniques of claim 38, the die further comprising:

a first character visible as a first color; and

a second character visible as a second color, which is different from the first.

43. (Previously Presented) The die with information deposited upon the die using semiconductor processing techniques of claim 38, further comprising a silhouette image in contact with the substrate and at least partially overlapping with at least one of the first or second paragraphs.

44. (Currently Amended) The die with information deposited upon the die using semiconductor processing techniques of claim 38, wherein:

the first paragraph corresponds to is-read-from an electronic source, which is used to generate the first paragraph;

the second paragraph corresponds to is-read-from the electronic source, which is used to generate the second paragraph; and

the column corresponds to is-generated-with an electronic file, which is used to generate the column.

45. (Previously Presented) The die with information deposited upon the die using semiconductor processing techniques of claim 38, wherein the first paragraph is deposited using a lithographic technique that includes a mask.

46. (Previously Presented) The die with information deposited upon the die using semiconductor processing techniques of claim 38, wherein the first paragraph is produced with a method comprising steps of:

converting a first character of the first paragraph into a first pattern;

converting a second character of the first paragraph into a second pattern; and

aligning the first and second characters on a line.

47. (Previously Presented) The die with information deposited upon the die using semiconductor processing techniques of claim 38, wherein the substrate is a semiconductor wafer.

48. (Previously Presented) The die with information deposited upon the die using semiconductor processing techniques of claim 38, wherein the first paragraph is produced with a method comprising a step of determining an end of a first line and beginning a second line.

49. (Previously Presented) The die with information deposited upon the die using semiconductor processing techniques of claim 38, wherein the column is produced with

a method comprising a step of determining an end of the first paragraph and beginning the second paragraph on the next line of the column.

50. (Previously Presented) The die with information deposited upon the die using semiconductor processing techniques of claim 38, wherein the column is produced with a method comprising a step of detecting an end of a first column and depositing a next line in a second column.

51. (Previously Presented) The die with information deposited upon the die using semiconductor processing techniques of claim 38, wherein the first paragraph is produced with a method comprising steps of:

- determining a first color for a first character; and
- determining a second color for a second character.

52. (Previously Presented) A die with information deposited upon the die using semiconductor processing techniques, the die comprising:

a substrate which is cut from a wafer comprising a plurality of substrates arranged in a grid of the wafer;

a paragraph photolithographically deposited upon the substrate; and
a silhouette image in contact with the substrate and at least partially overlapping with the paragraph.

53. (Previously Presented) The die with information deposited upon the die using semiconductor processing techniques of claim 52, wherein the paragraph is derived from an electronic file that comprises a plurality of elements corresponding to characters for the paragraphs.

54. (Previously Presented) The die with information deposited upon the die using semiconductor processing techniques of claim 52, wherein each character of the paragraph is comprised of a plurality of rectangles wherein one side of the rectangle is equal in size to the process resolution.

55. (Previously Presented) The die with information deposited upon the die using semiconductor processing techniques of claim 52, the die further comprising:

- a first character visible as a first color; and
- a second character visible as a second color, which is different from the first.

56. (Currently Amended) The die with information deposited upon the die using semiconductor processing techniques of claim 52, wherein:

the paragraph corresponds with is read from an electronic source, which is used to automatically generate the paragraph; and

the silhouette image is generated corresponds with an electronic file, which is used to automatically generate the silhouette image.

57. (Previously Presented) The die with information deposited upon the die using semiconductor processing techniques of claim 52, wherein the paragraph is deposited using a lithographic technique that includes a mask.

58. (Previously Presented) A die with information deposited upon the die using semiconductor processing techniques, the die comprising:

- a substrate which is cut from a wafer comprising a plurality of substrates arranged in a grid of the wafer;
- a first paragraph photolithographically deposited upon the substrate;
- a second paragraph photolithographically deposited upon the substrate; and
- a silhouette image in contact with the substrate and at least partially overlapping at least one of the first or second paragraphs.

59. (Previously Presented) The die with information deposited upon the die using semiconductor processing techniques of claim 58, the die further comprising:

- a first character visible as a first color; and
- a second character visible as a second color, which is different from the first.

60. (Currently Amended) The die with information deposited upon the die using semiconductor processing techniques of claim 58, wherein:

the first paragraph is generated automatically read from using an electronic source containing the first paragraph; and

the second paragraph is generated automatically read from using an electronic source containing the second paragraph; and

the column is generated with an electronic file.

61. (Previously Presented) The die with information deposited upon the die using semiconductor processing techniques of claim 58, wherein the first paragraph is deposited using a lithographic technique that includes a mask.

62. (Previously Presented) A die with information deposited upon the die using semiconductor processing techniques, the die comprising:

a substrate which is cut from a wafer comprising a plurality of substrates arranged in a grid of the wafer;

a first paragraph photolithographically deposited upon the substrate, wherein the first and second paragraphs are comprised of a plurality of characters;

a second paragraph photolithographically deposited upon the substrate wherein at least one of the first or second paragraphs is generated with an electronic file; and

a silhouette image in contact with the substrate and at least partially overlapping at least one of the first or second paragraphs.